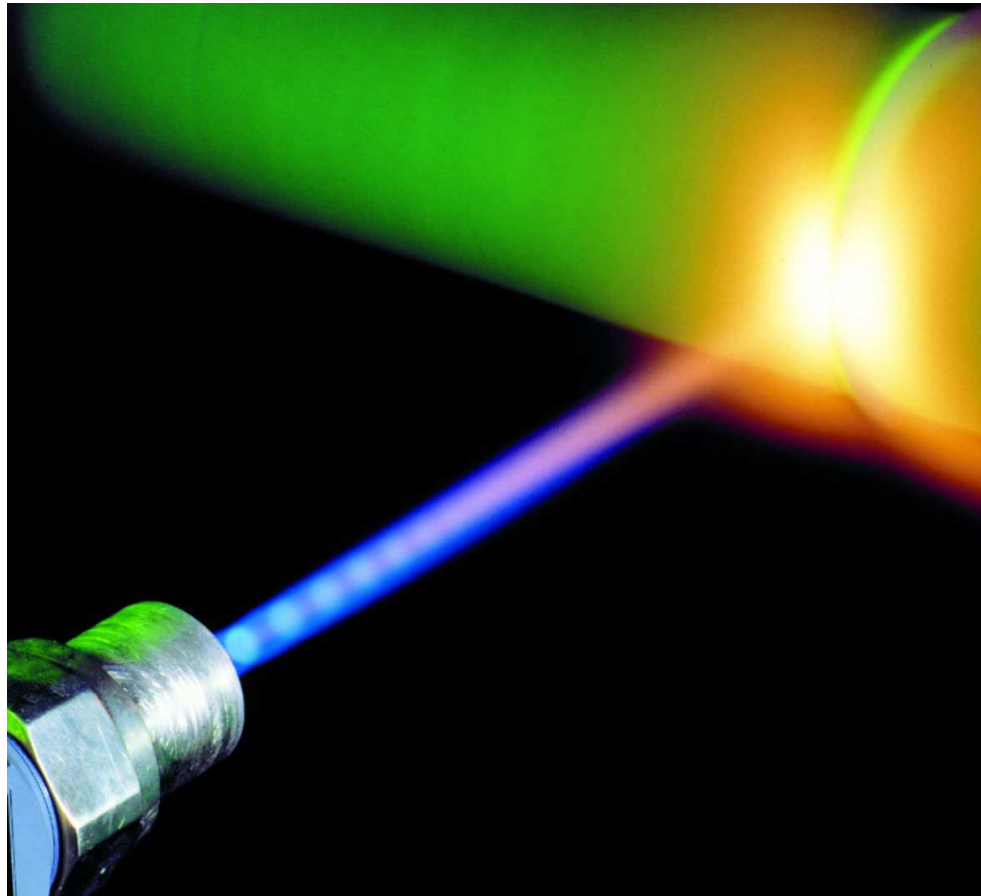


# LASERY



# Čištění laserovým paprskem

Nd:YAG  
Excimer  
Er:YAG  
Pulsní CO2

Black crust  
Patina  
Calcite



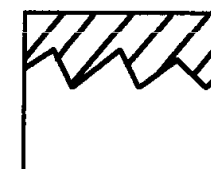
Weathered profile



Ideal cleaning



Conventional  
cleaning



Laser cleaning

## *Průmysl:*

Polymerní povlaky  
Koroze  
Ropné produkty  
Částice nečistot  
Dezinfekce

## *Ochrana KD:*

Koroze  
Inkrustace  
Sediment  
Mikroorganismy  
Graffiti  
Přemalby

# Čištění laserovým paprskem

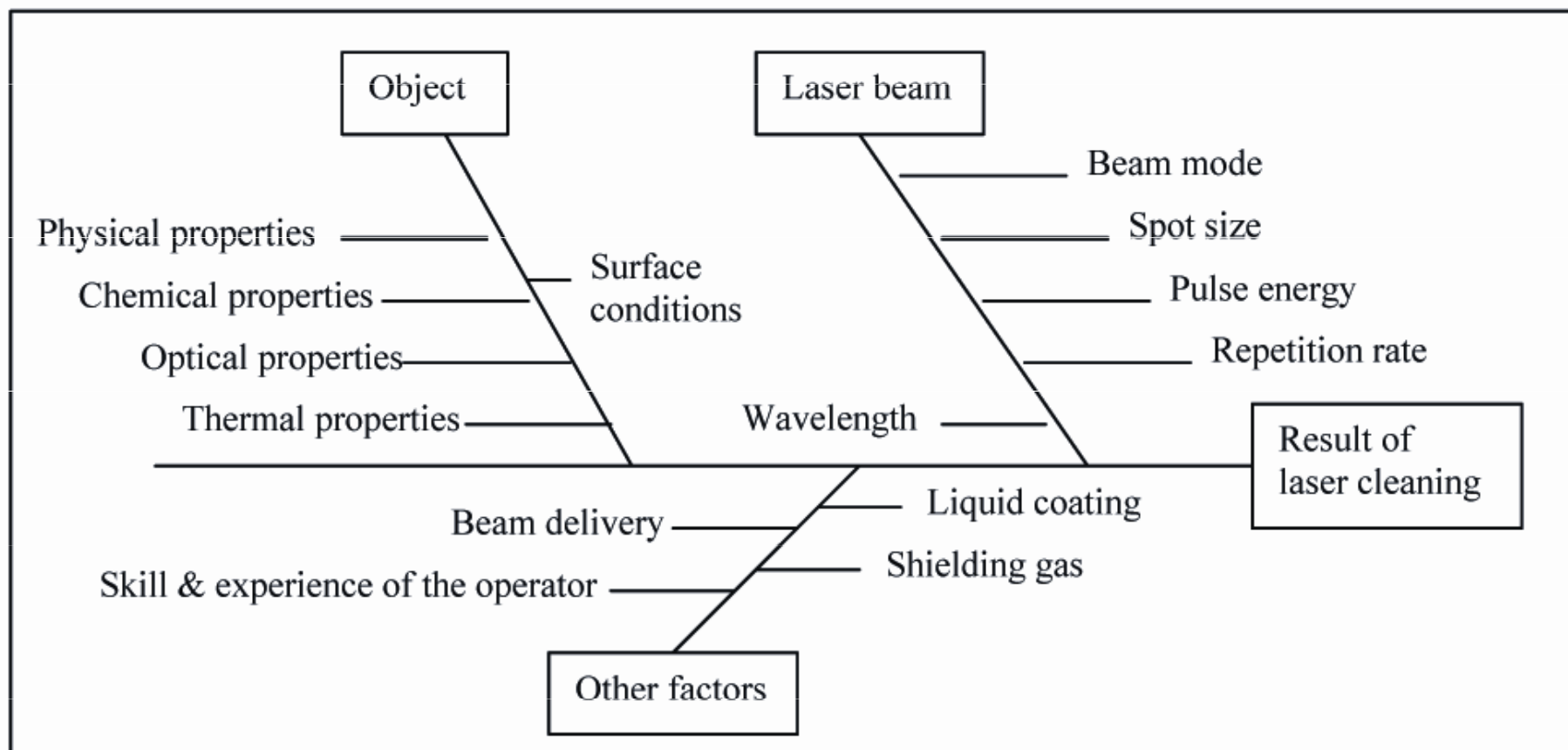
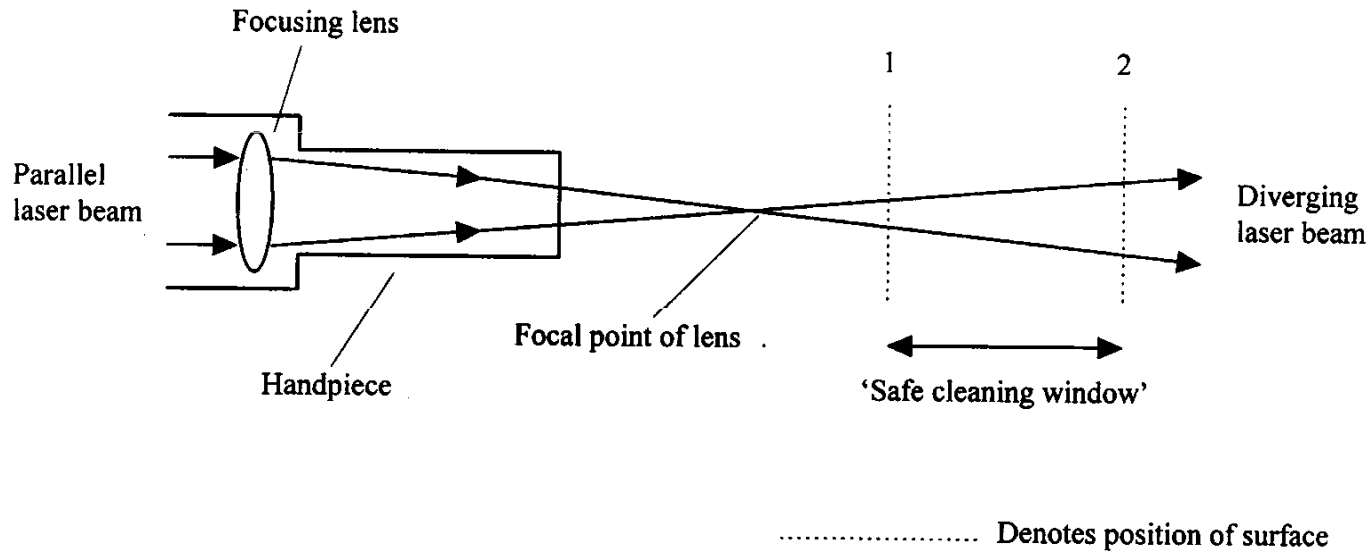


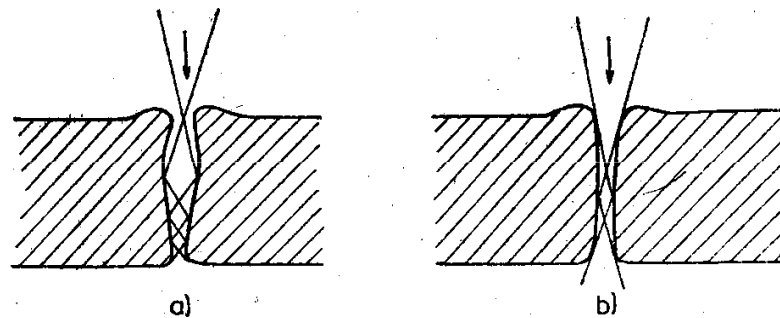
Figure 4. Ishikawa diagram of the factors affecting the laser cleaning process

# Mechanismy čištění laserem

# Fokusace laserového paprsku



**Figure 4.2.** Schematic representation of cleaning with a diverging laser beam.



**Obr. 64.** Řez kráterem vypáleným laserovým svazkem při různých polohách ohniska fokusační techniky: a) ohnisko při povrchu materiálu, b) ohnisko pod povrchem

before laser cleaning

while laser cleaning

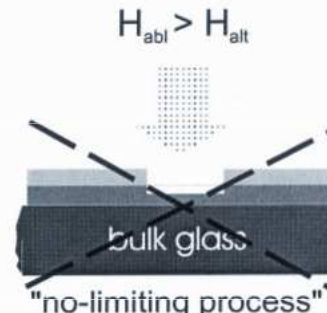
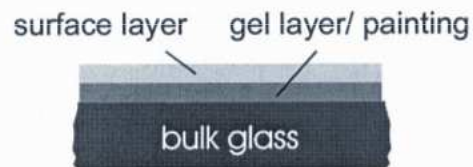
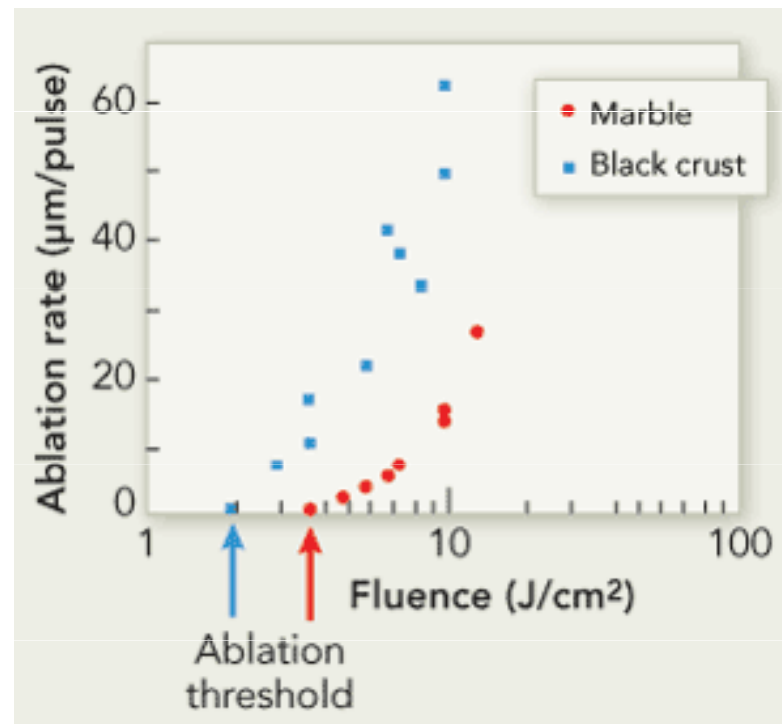
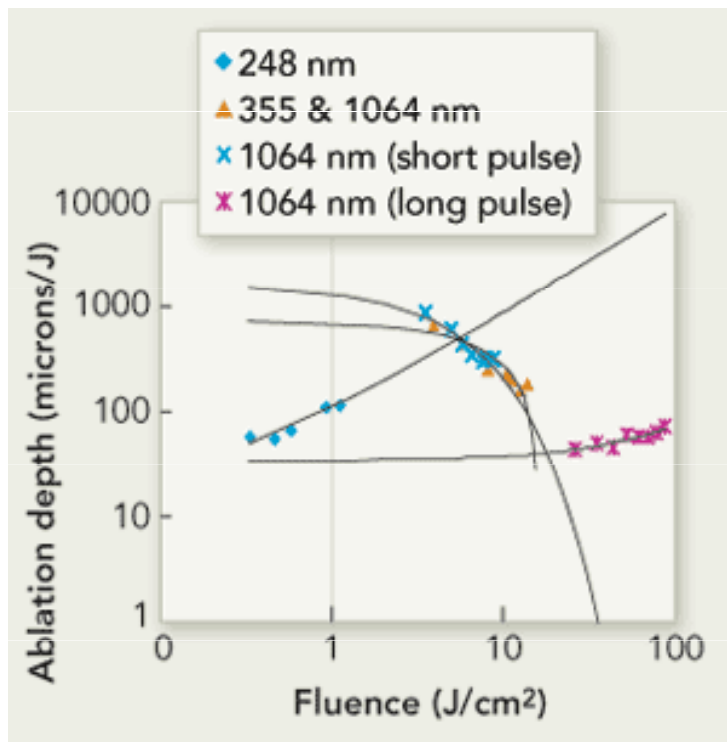


Figure 6. Schematic presentation of the assumed ablation characteristics of different layers and the consequences for the ablation process ( $H_{abl}$  = ablation threshold,  $H_{alt}$  = alteration threshold).



# OPTICAL ABSORPTION

## Below vaporization threshold

$t_L \sim 1-10 \text{ ns}$ ,  $t_L < t_{st}$   
 $10^7-10^8 \text{ W/cm}^2$

$t_L \sim 1-10 \text{ ns}$ ,  $t_L > t_{st}$   
 $10^7-10^8 \text{ W/cm}^2$

Pressure  
confinement

Thermoelastic  
expansion

High pressure  
gradient at  
the interface

Double phase  
pressure wave

**Impulsive ejection**

**Spallation**

## Above vaporization threshold

$t_L \sim 1-100 \text{ ns}$   
 $10^7-10^9 \text{ W/cm}^2$

$t_L \sim 1-10 \mu\text{s}$   
 $1-10 \text{ J/cm}^2$

No breakdown

Breakdown

Thermoelastic  
phase

Ionization  
Dense plasma

Possibility of a  
rarefied plasma

Fast thermal  
explosion

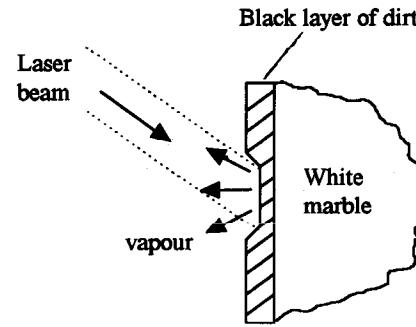
Plasma  
expansion  
Shock wave

Quasi-sonic  
expansion

**Explosive removal**  
**Recoil stress**

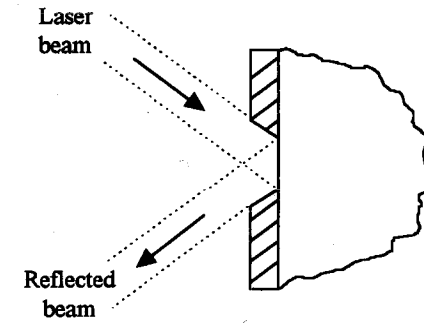
**Strong recoil**  
**Mechanical destr.**

**Fast vaporization**



Absorption of laser beam

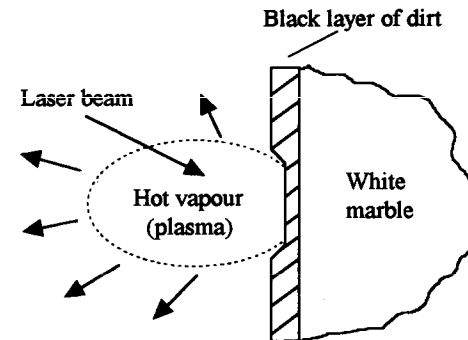
Initial interaction of long pulse radiation with a dark encrustation. Strong absorption of energy leads to vaporisation of material.



Reflection of laser beam

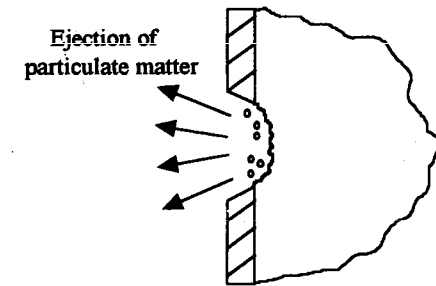
Final interaction of long pulse radiation with a dark encrustation. Once the encrustation has been removed further pulses are reflected from the weakly absorbing marble surface.

Figure 1.3. Normal-mode cleaning (Asmus, 1973).



Beginning of laser pulse

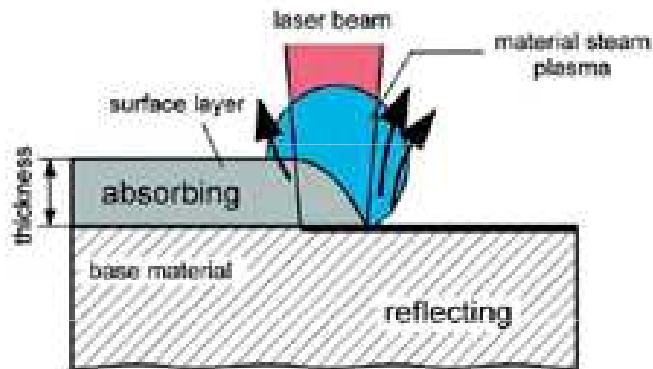
Vaporisation of encrustation occurs early during the pulse, leading to formation of a plasma. The temperature and pressure of the plasma increase rapidly as the incoming laser radiation is absorbed and a microscopic compression is applied to the surface.



End of same laser pulse

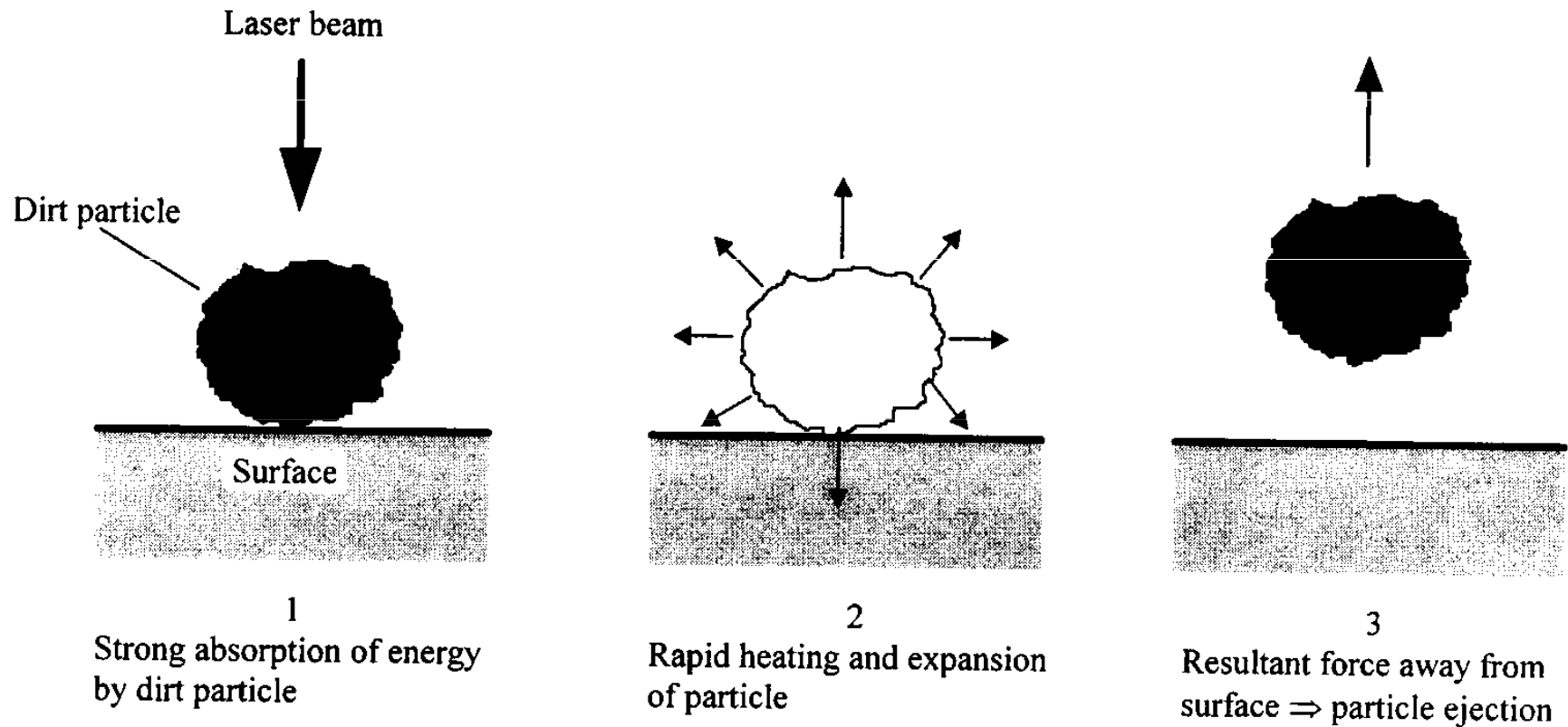
As soon as the laser pulse finishes the plasma expands away from the surface. The surface relaxes and a thin layer of material is ejected.

Figure 1.4. Removal of material by Q-switched laser radiation (Asmus, 1973).



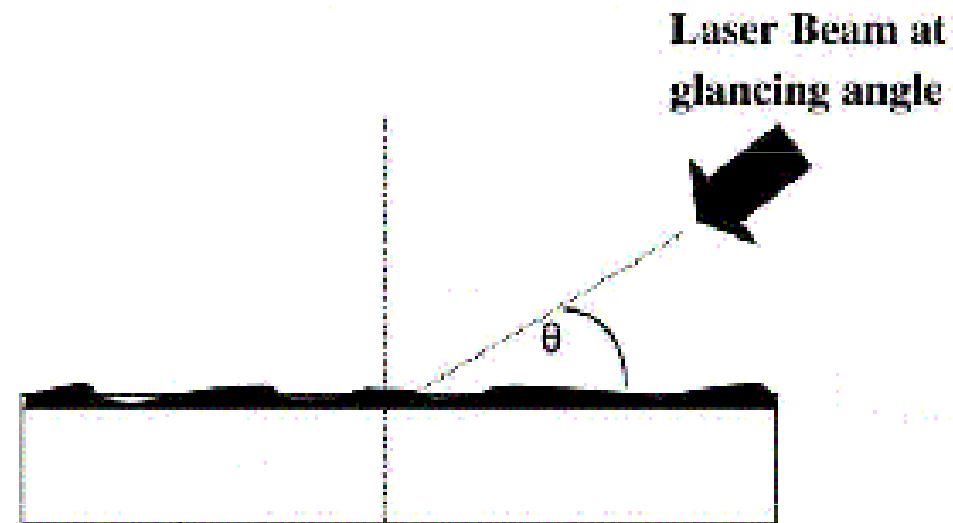


# Termická expanze částic



*Removal of dirt particles by rapid thermal expansion.*

# Angulární čištění ( $\alpha < 90^\circ$ )



Efektivnější než klasicky používané kolmé uspořádání, největší absorptivita při Brewstrově úhlu.

Index lomu materiálu =  
 $\tan(\text{Brewstrová úhlu})$ .

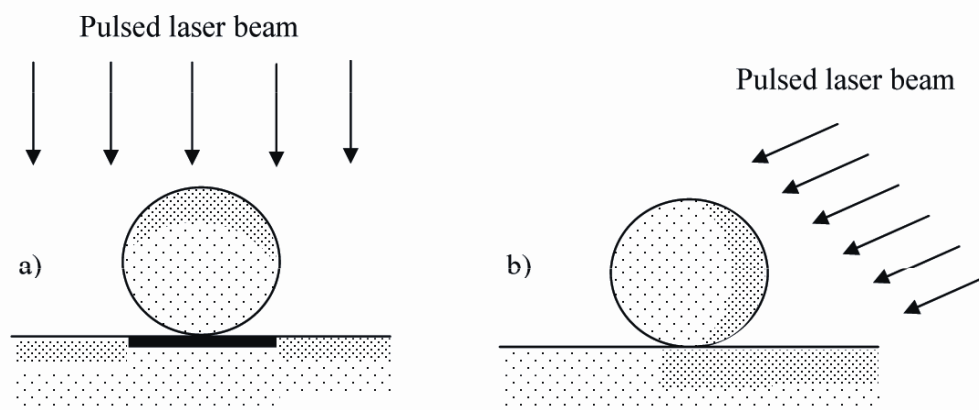


Fig. 3. Illustration of the laser absorption on the surfaces of the particle and the substrate for different laser incident angles (The density of "dots" indicates the amount of heating due to the laser absorption on the surfaces)

# Čištění rázovou vlnou

Je účinná jen pro malé a silně vázané částice, pro čištění památek se nepoužívá.

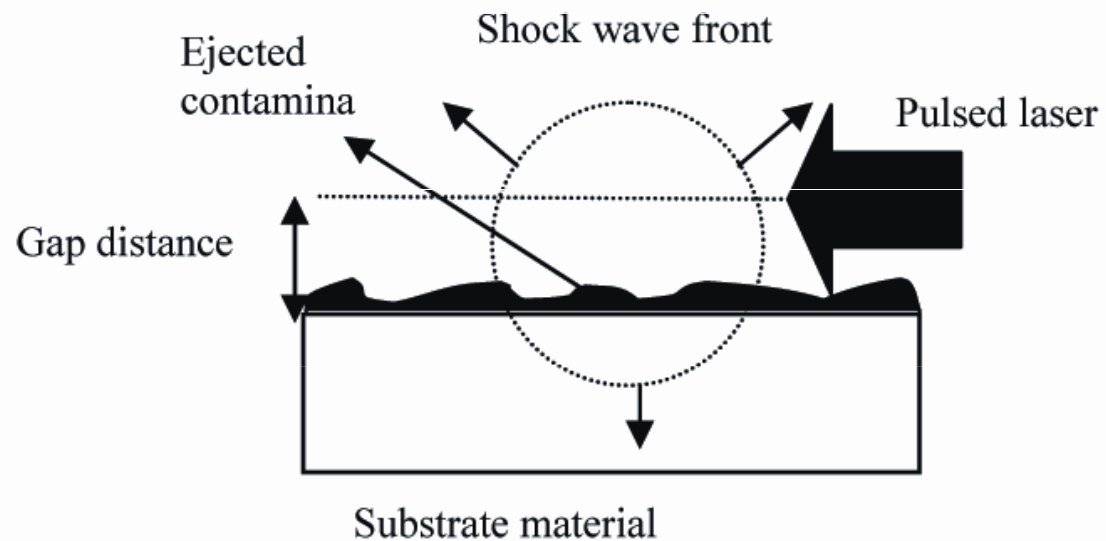


Fig 4: Schematic diagram of laser shock cleaning

# Steam cleaning

= aplikace filmu kapaliny na povrch artefaktu

- Nečistoty jsou vázány pevně na povrch artefaktu a nelze je odstranit suchým čištěním.
- Povrch artefaktu je křehký a je tedy třeba použít menší hustotu energie.

Nejpoužívanější kapalinou je voda, možné je i použití organických rozpouštědel.

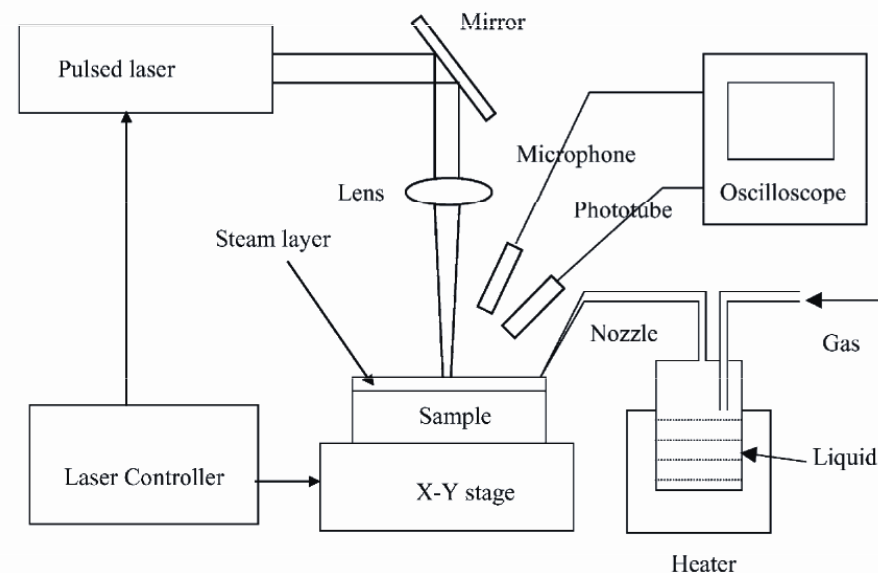
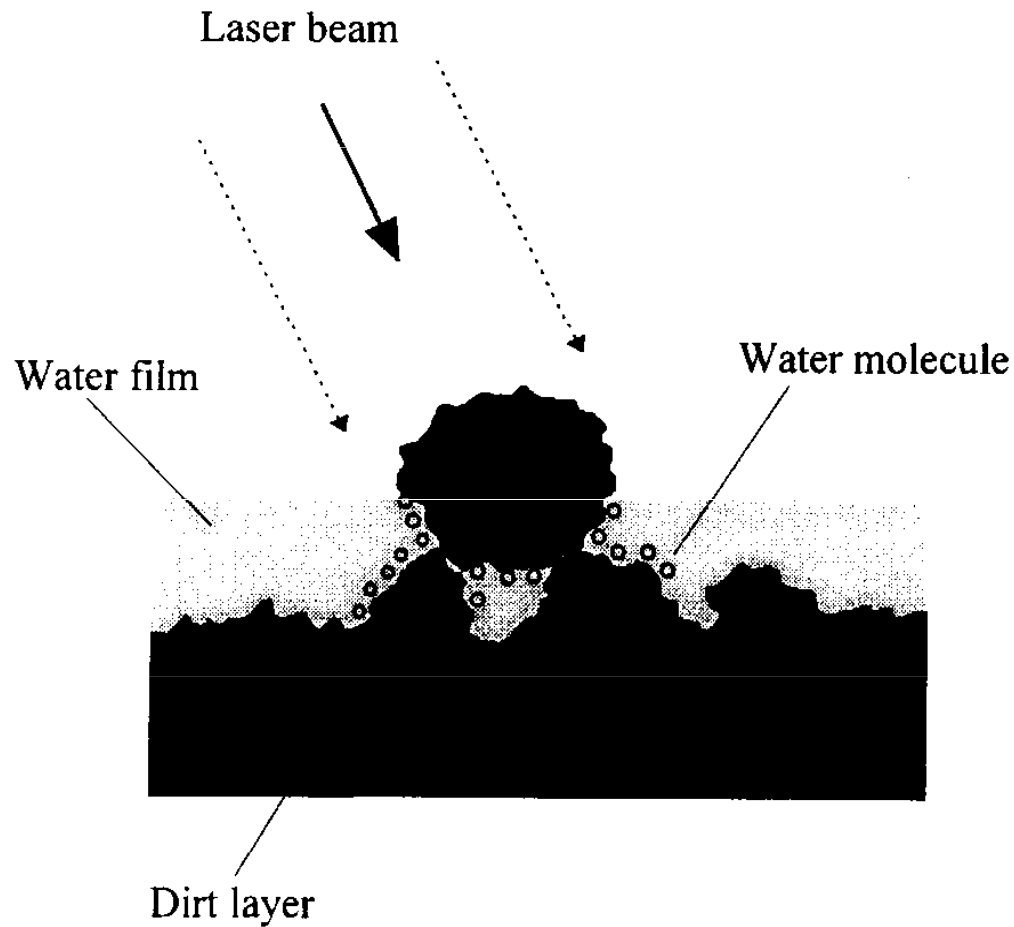


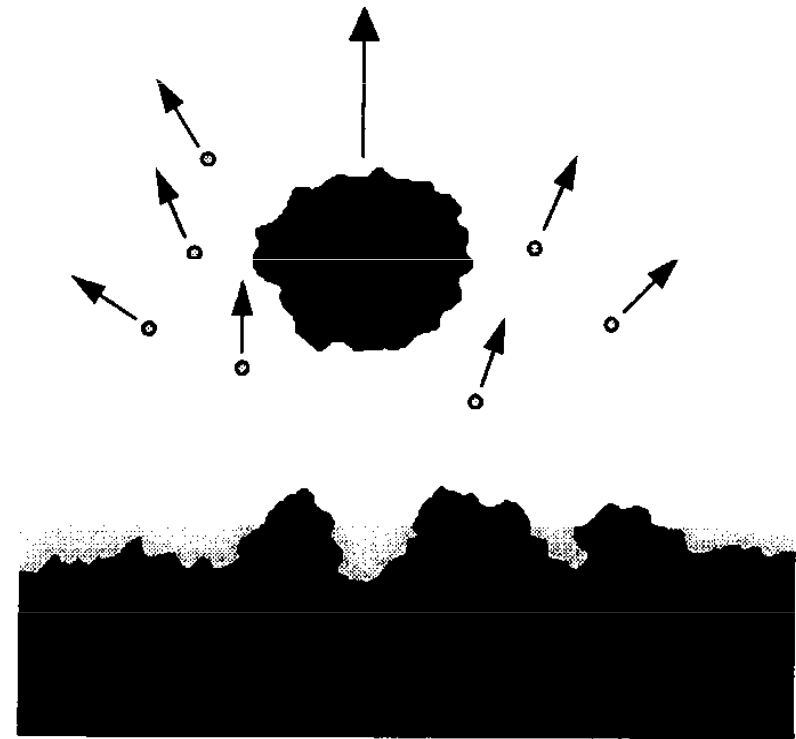
Fig. 1. Experimental set-up for steam-assisted laser ablation.

Kavitace – další možný mechanismus

# Ablace v kapalině



Absorption of energy by dirt layer.  
Rapid heating of water molecules at  
water/dirt interface.



Explosive vaporization of water enhances  
dirt removal from surface

# Ablace koroze v kapalině (s vloženým napětím)

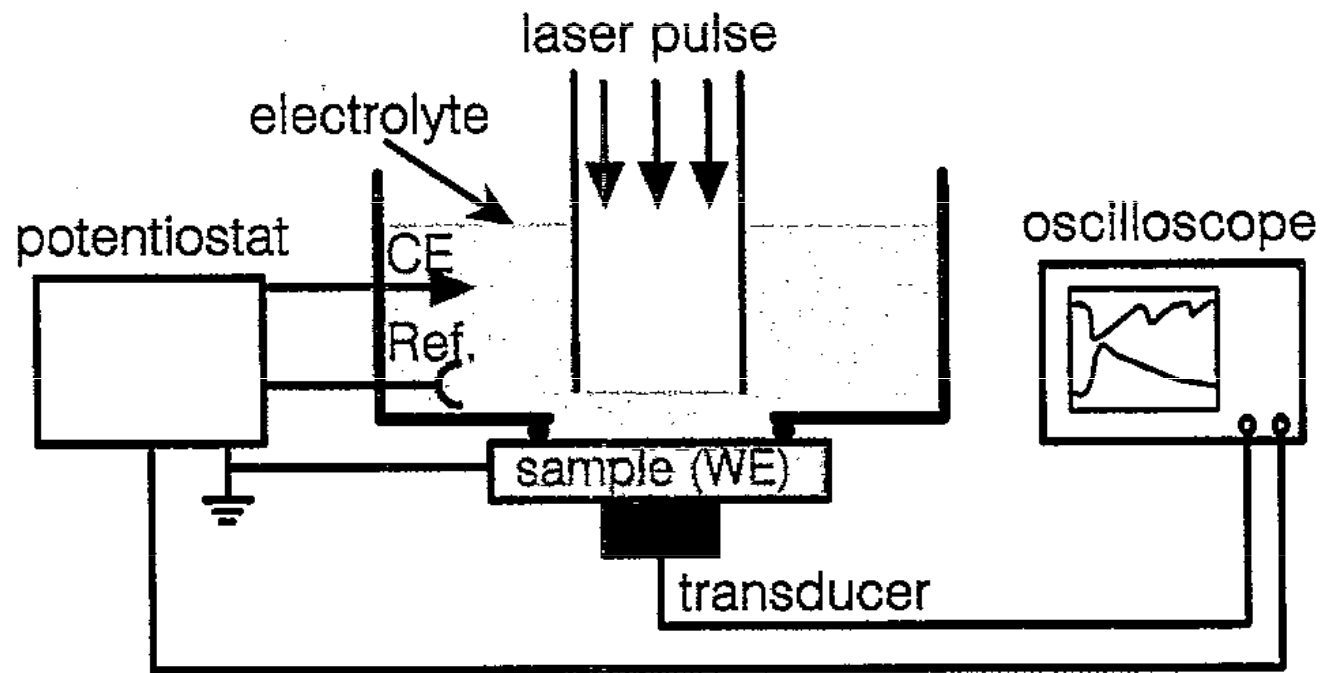
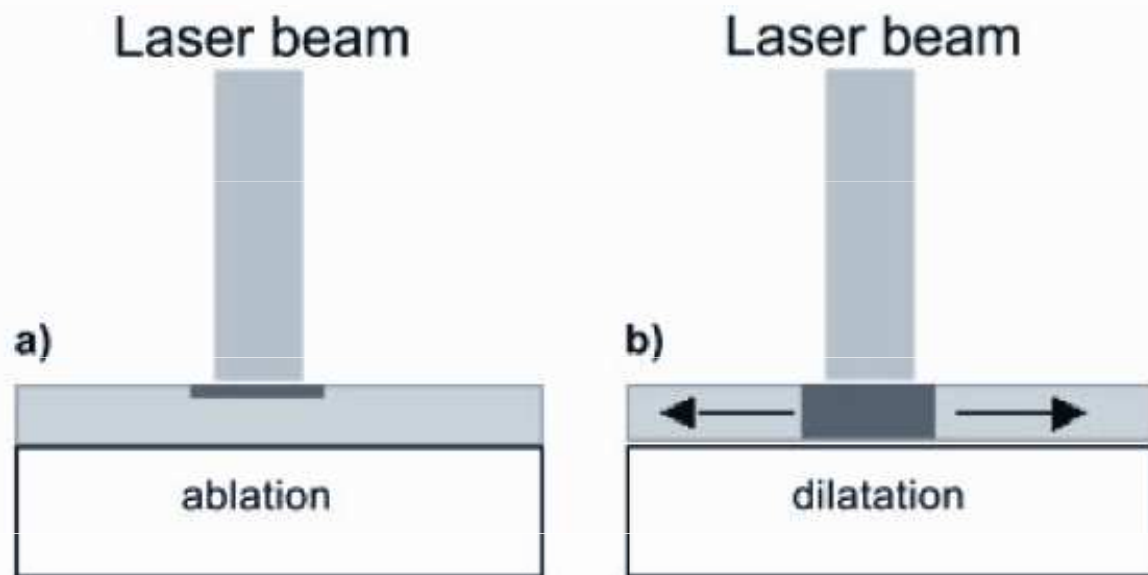


Fig. 1. Experimental configuration for the laser-induced oxide film removal in a liquid confinement at controlled electrochemical potential. Ref., reference electrode; CE, counter electrode; and WE, working electrode.



**Fig. 4a,b.** Schematic picture of the energy absorption in the  $\text{Fe}_3\text{O}_4$  layer **a** before and **b** after electrochemical polarisation

Na železný předmět v borátovém pufru ( $\text{pH} = 10$ ) v tříelektrodovém uspořádání (předmět = katoda) se vloží kontrolovaný potenciál ( $-2 \text{ V}$ ). Vodík vznikající katodickou redukcí se zachycuje na oxidové vrstvě. Laserový puls (Nd:YAG 1064 nm) způsobí rozpínání vodíku a mechanickou destrukci korozní vrstvy. Monitorování průběhu čištění se provádí např. cyklickou voltametrií.

# Aplikace laserů pro likvidaci mikroorganismů

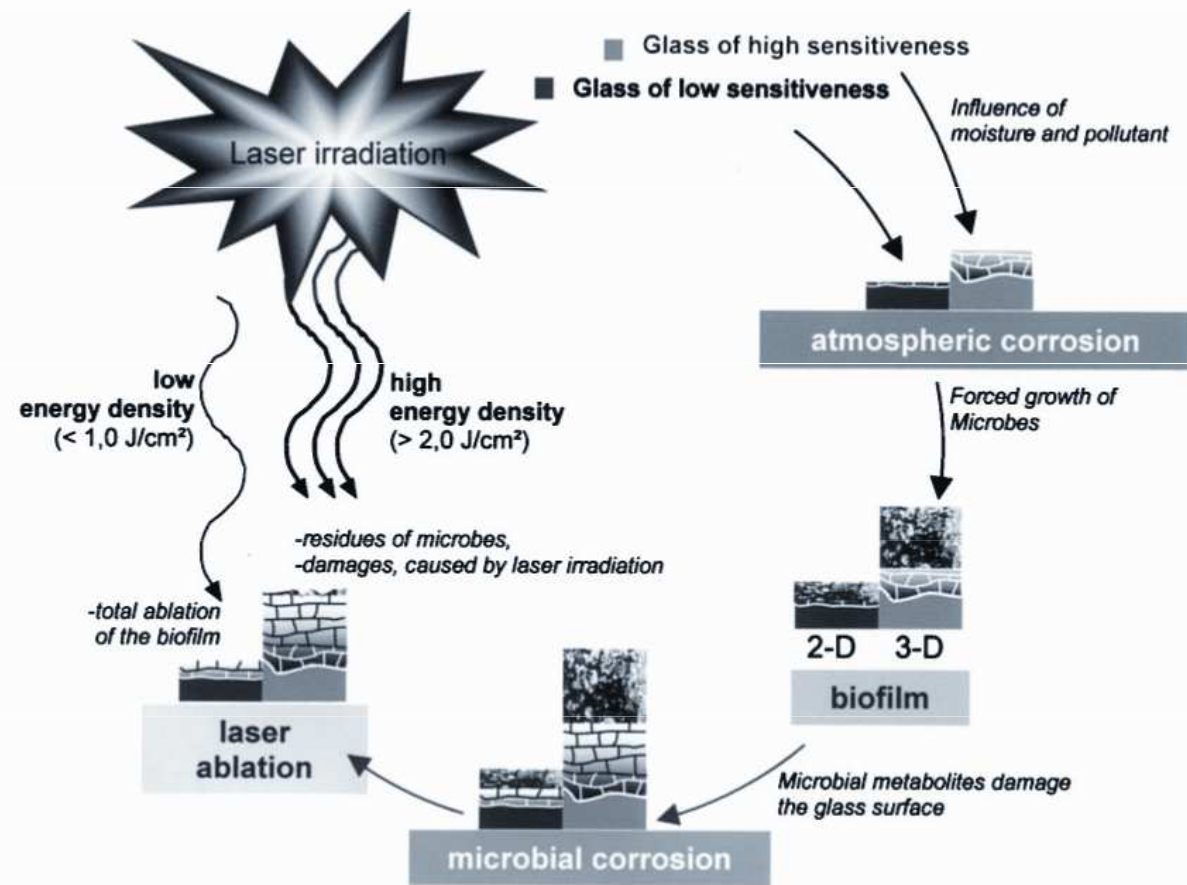
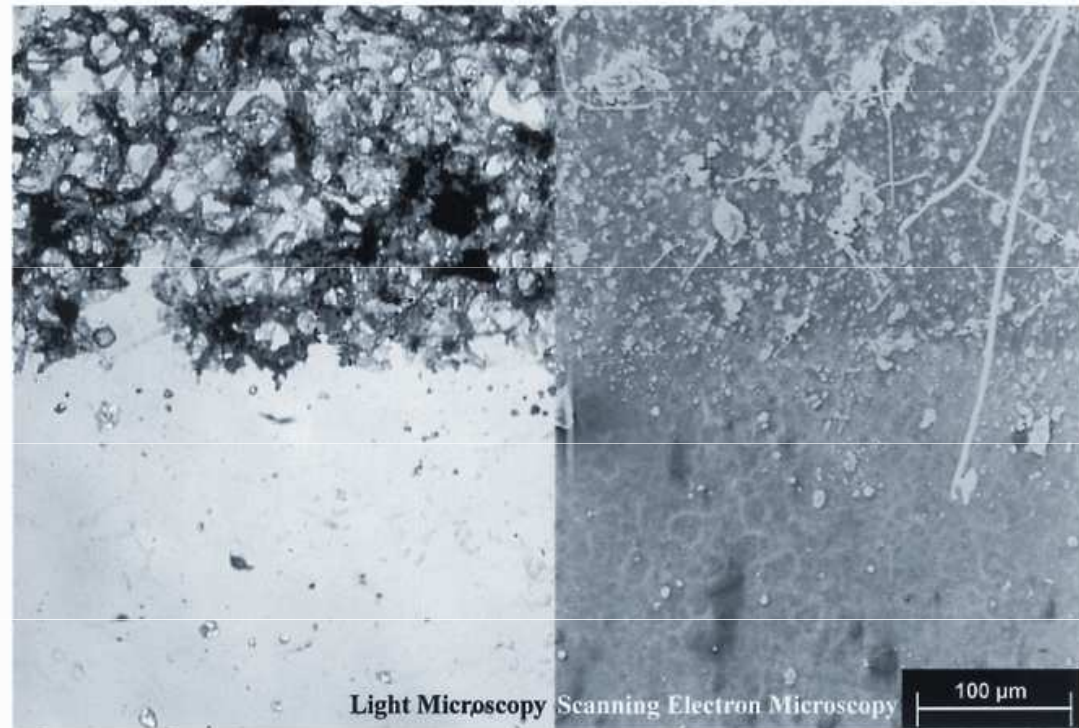


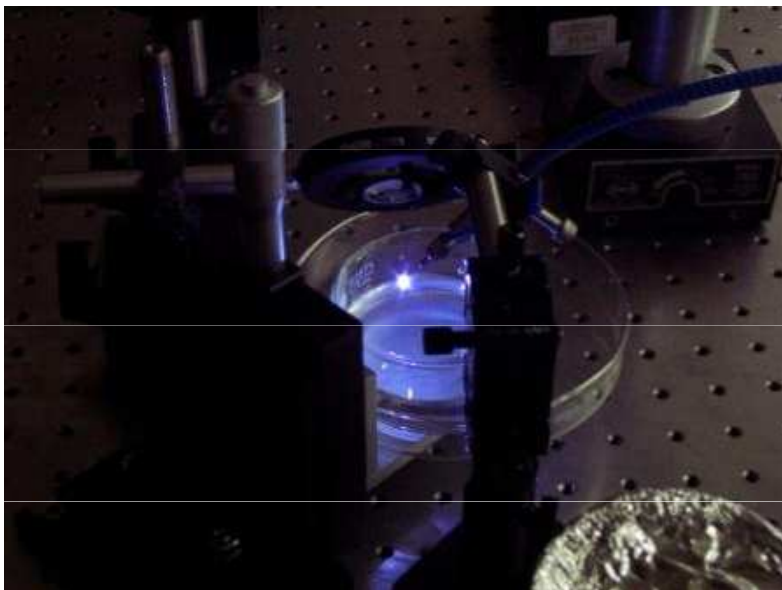
Figure 10. Interaction of glass and biofilm and the synergetic effect of glass composition, abiotic corrosion, biogenic corrosion and growth of biofilm, factors which influence the effectiveness of the laser cleaning.



- Bakterie
- Plísně
- Lišejníky

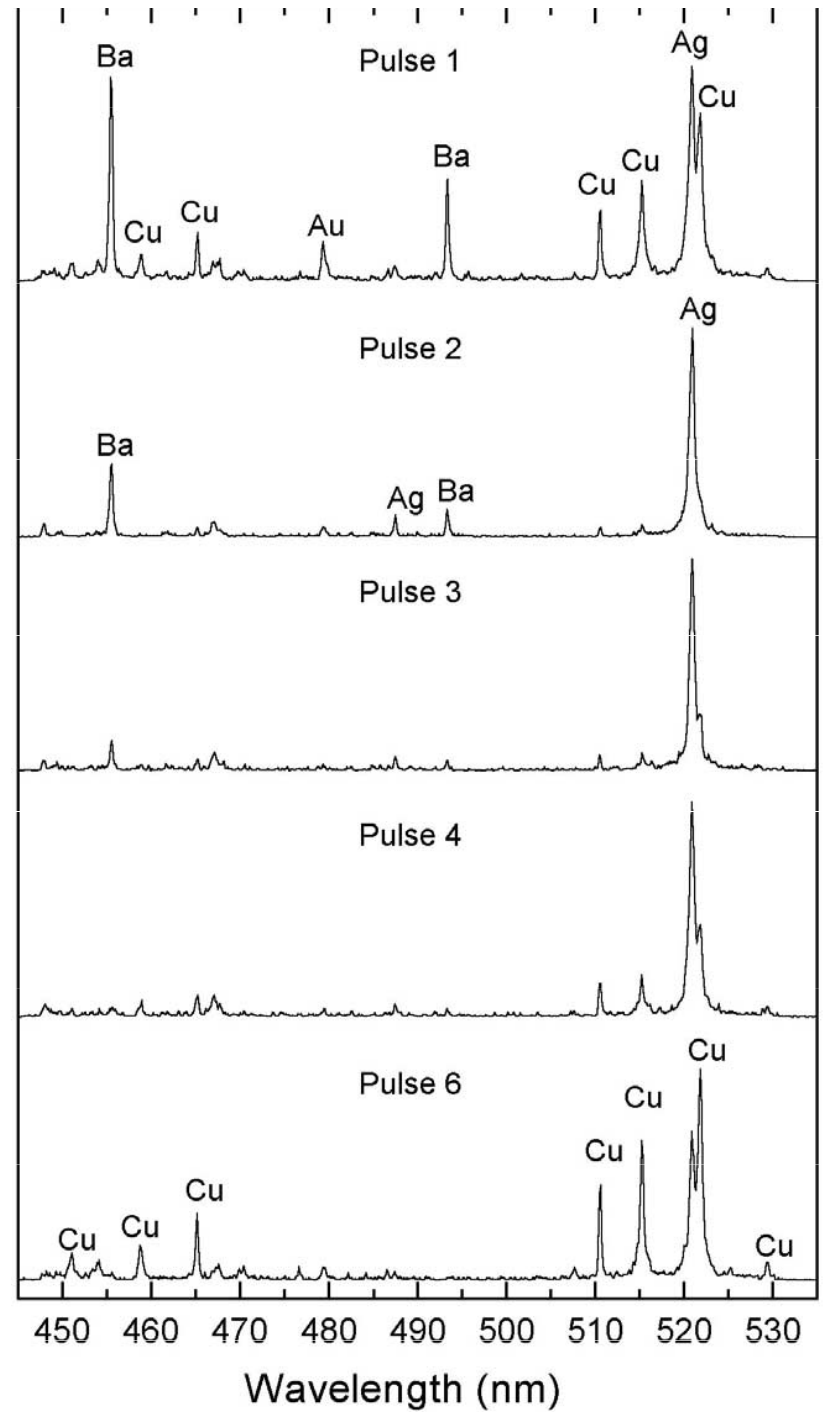
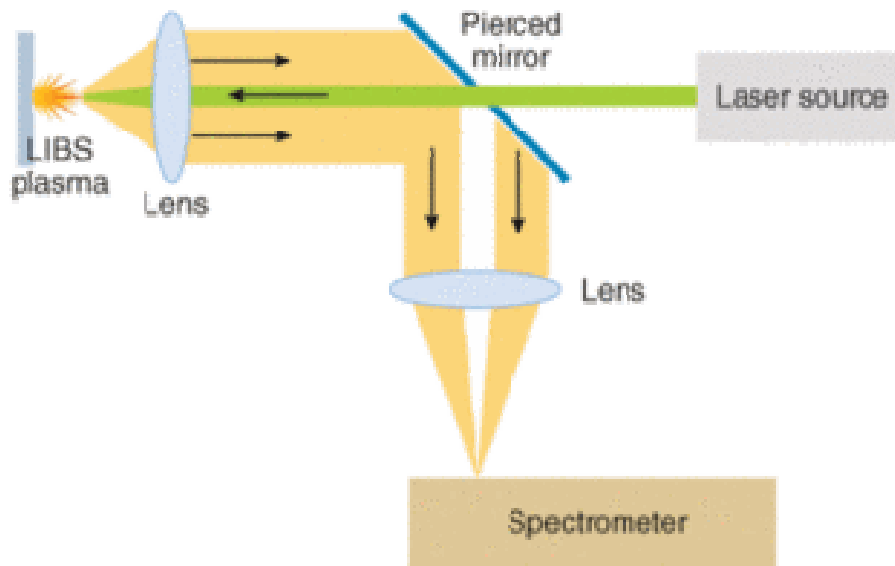
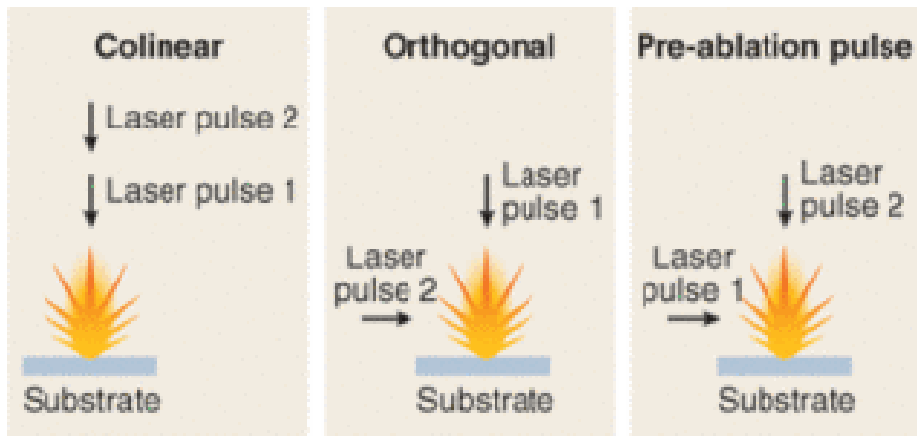


**Figure 2.** The laser cleaning of two-dimensional biofilms is successful with an energy density of  $1.0 \text{ J/cm}^2$ .

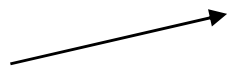


# Monitorování procesu Iserového čištění

# LIBS

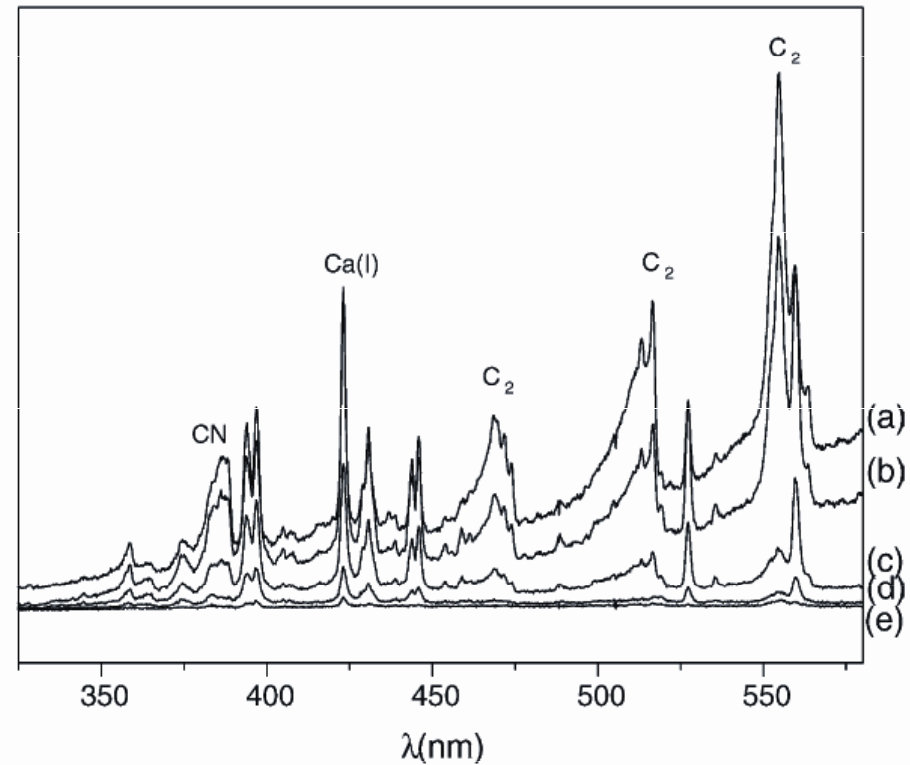


Daguerrotypie, 19. stol.



# LIBS

Molekulové pásy



Spojení s Ramanovou spektrometrií

Fig. 6. Evolution of LIBS spectrum with the number of pulses during the removal of black paint on wood: (a) pulse 1, (b) pulse 2, (c) pulse 4, (d) pulse 7 and (e) pulse 9. Irradiation wavelength: 308 nm.

## Měření na dané čáře v UV-VIS

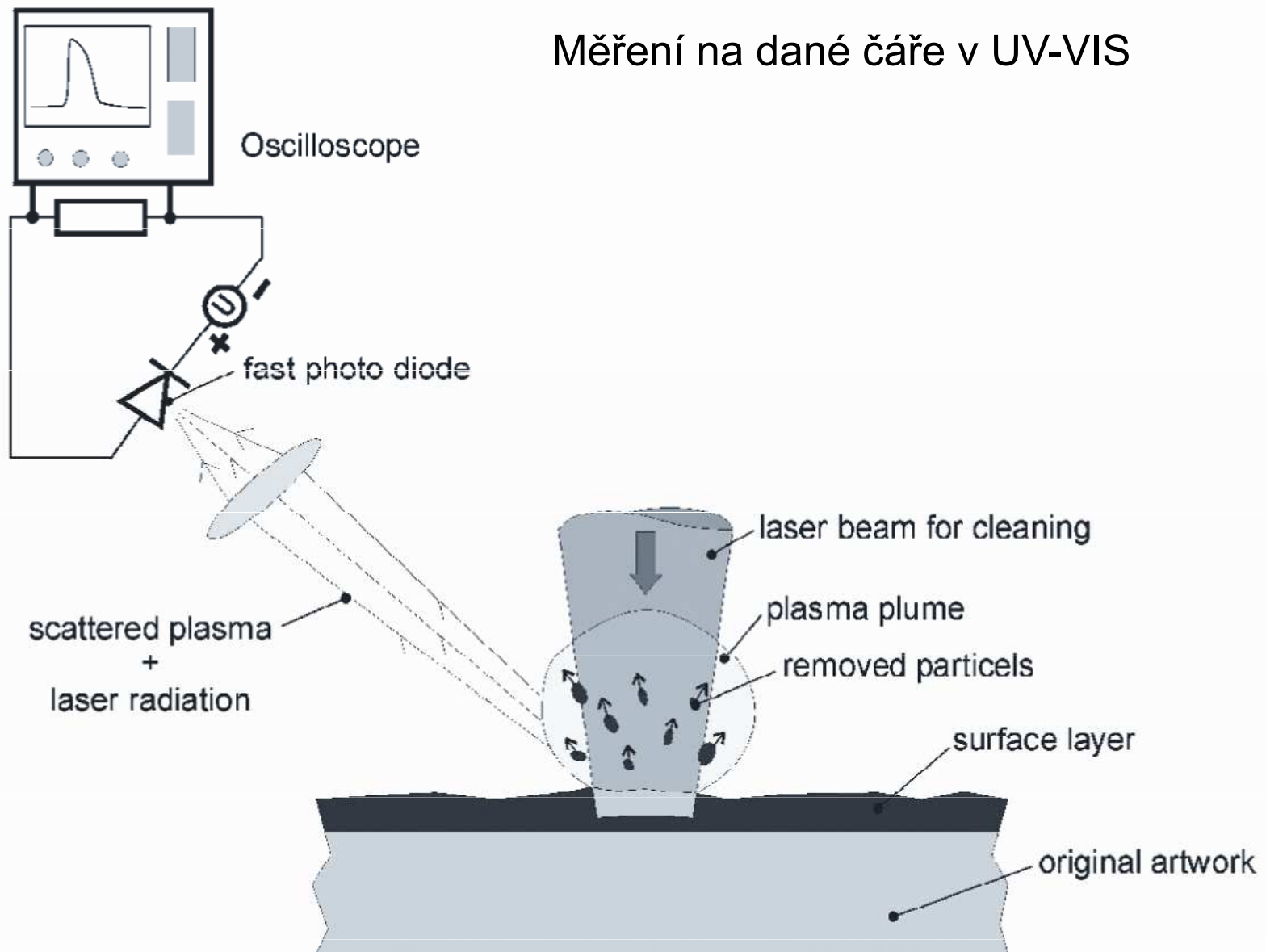


Fig. 1. Experimental set-up for detection of the scattered radiation during laser cleaning.

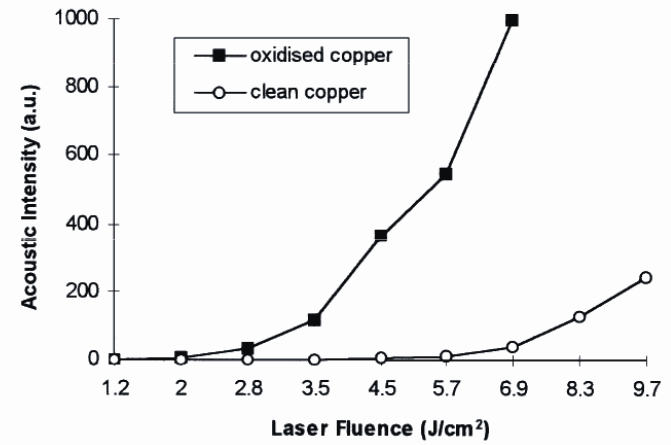
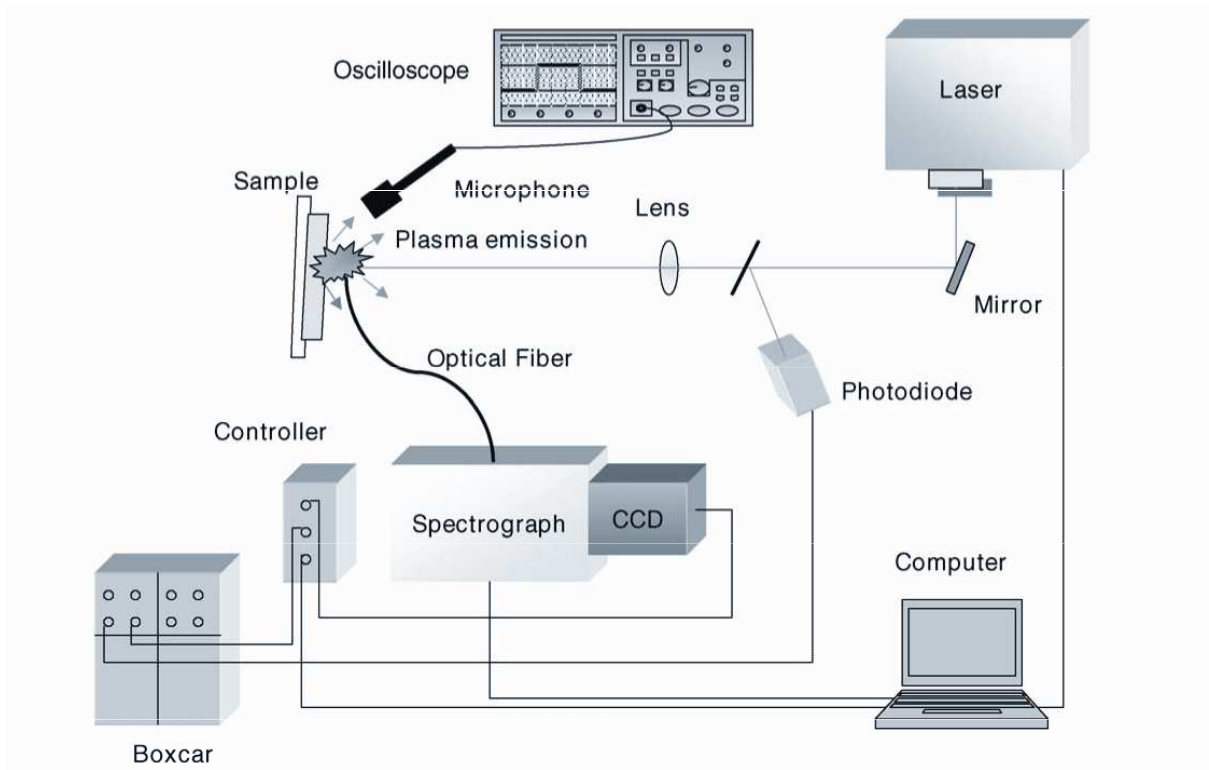


Fig. 3. Acoustic emission intensity as a function of laser fluence in the laser treatment of an oxidised copper surface and a clean copper surface.



Schematic diagram of the experimental set-up used for the LIBS experiments and for the photoacoustic measurements.

# Sledování akustického projevu

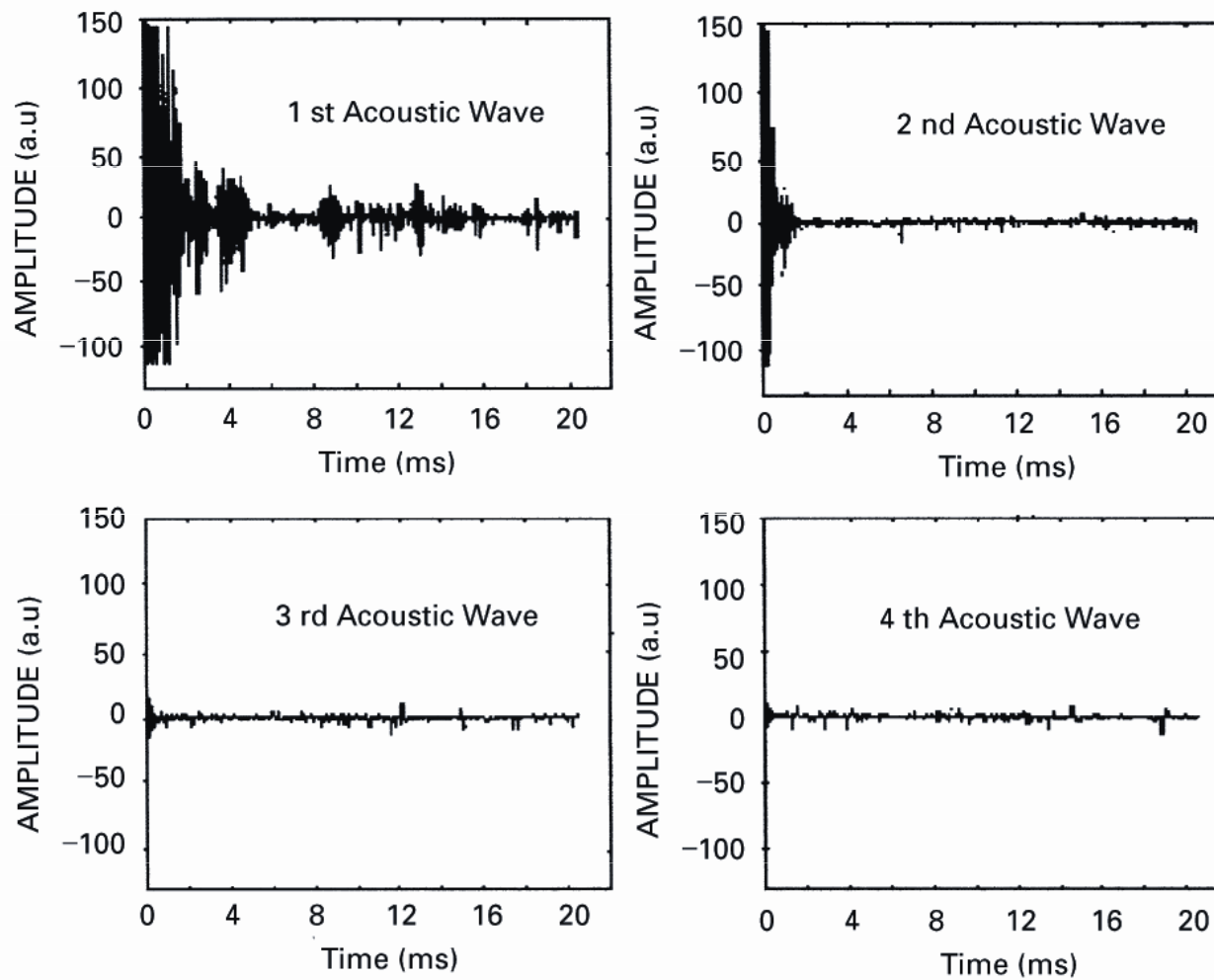
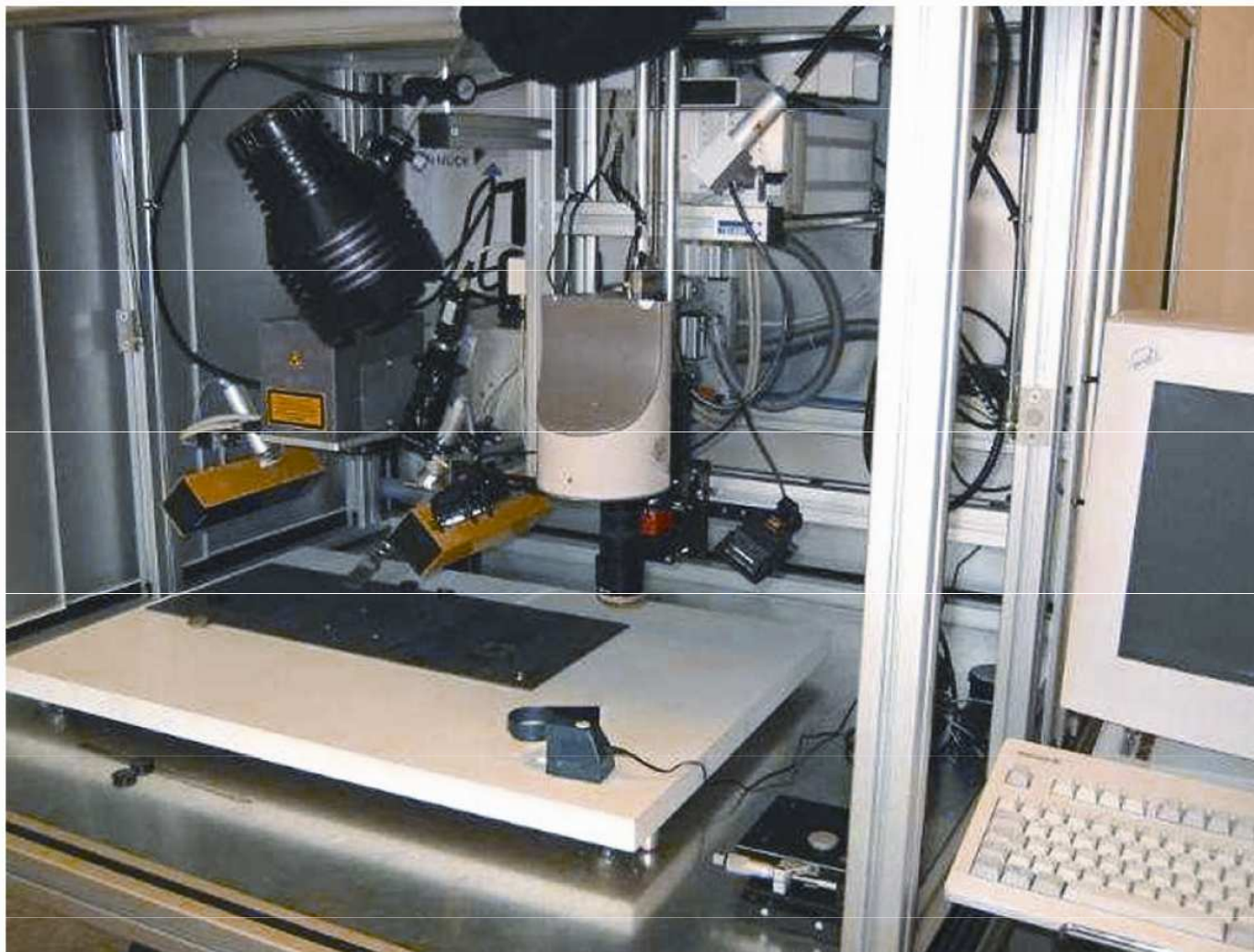


Fig. 2. Acoustic waves emitted from an oxidised copper substrate under laser irradiation from the first to the fourth pulse, respectively.

# Zařízení na laserové čištění uměleckých artefaktů





**Figure 6.**

The laser system developed for the cleaning of paper and parchment is organised in a closed box, providing maximum safety of operation. The set-up includes besides the laser imaging systems and a positioning table.

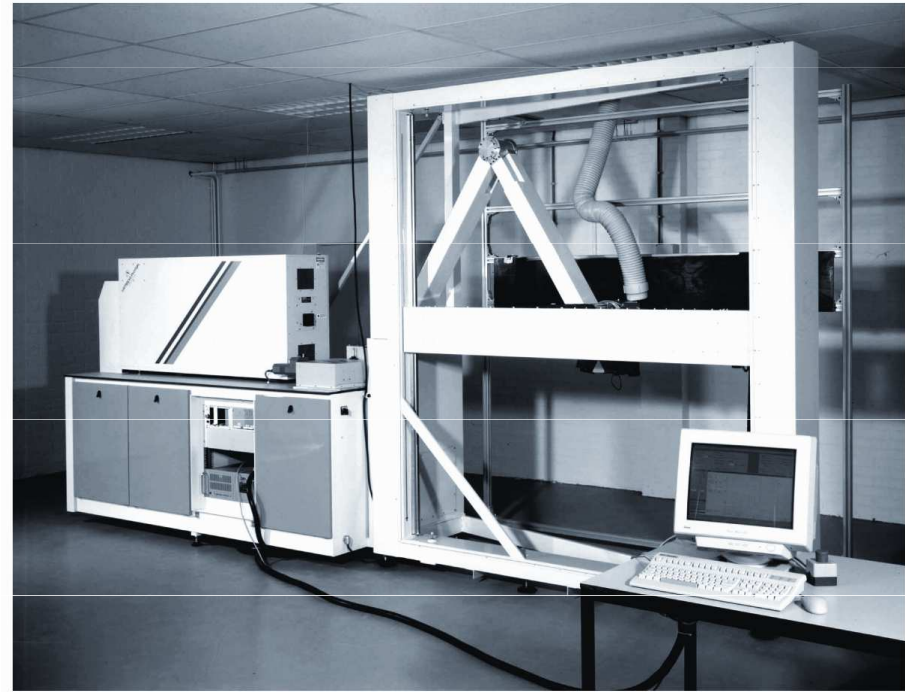


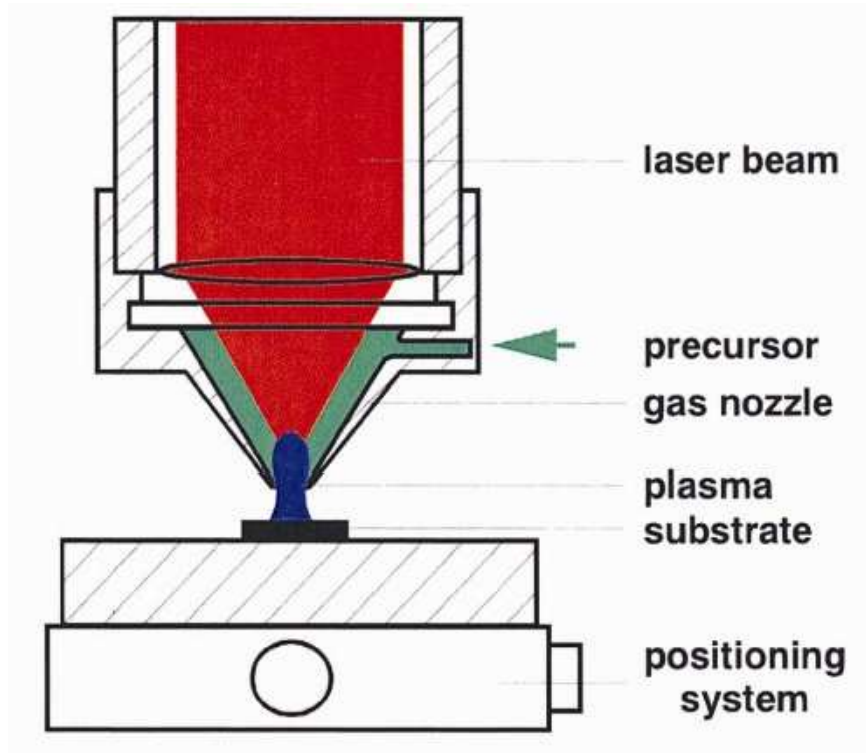


Plate 4.1. Laser cleaning of sculptural detail on the outside of a building.



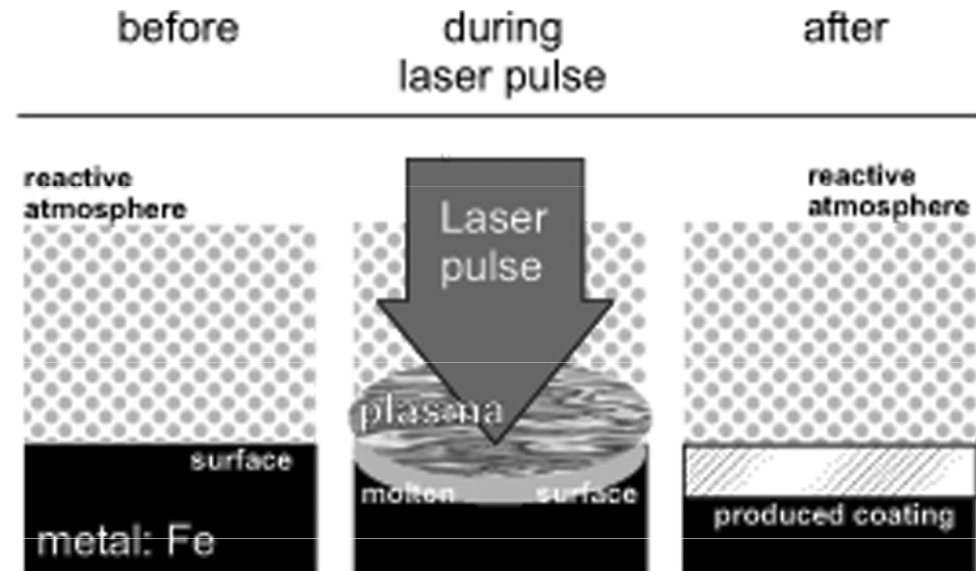
# Povrchové úpravy

# Nitridace a karburizace povrchu



Nitridace ( $N_2$ )

Karburizace ( $CH_4$ )



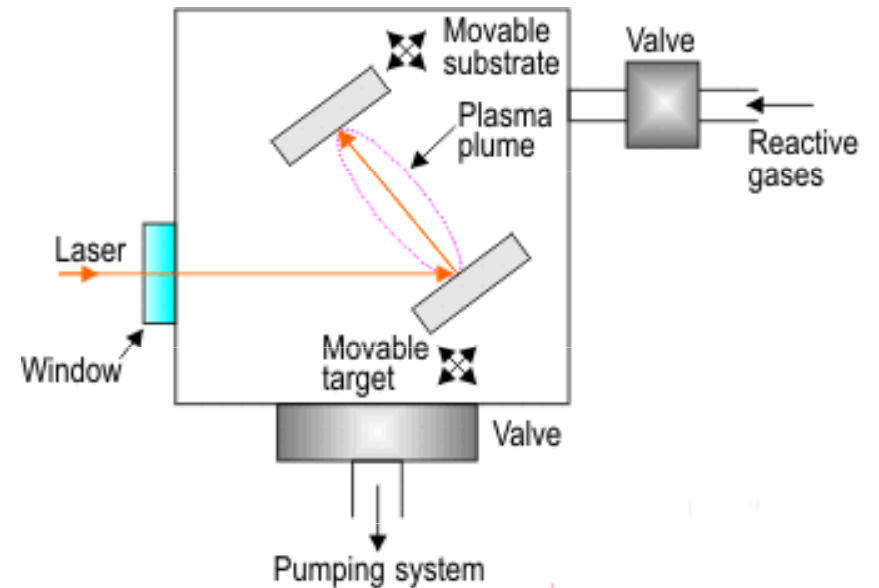
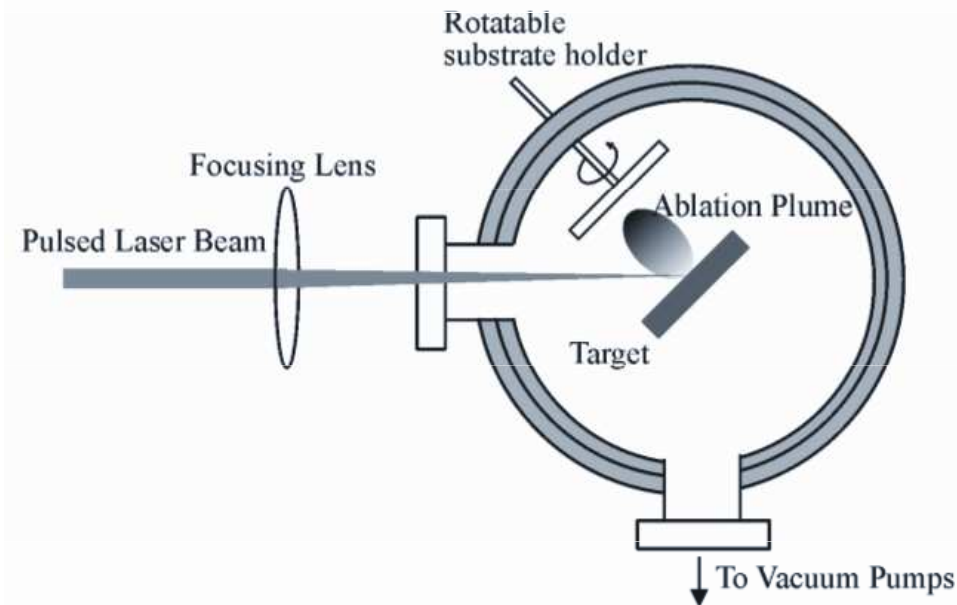
Snaha zabránit korozi železa.

# Naprašování povrchových vrstev

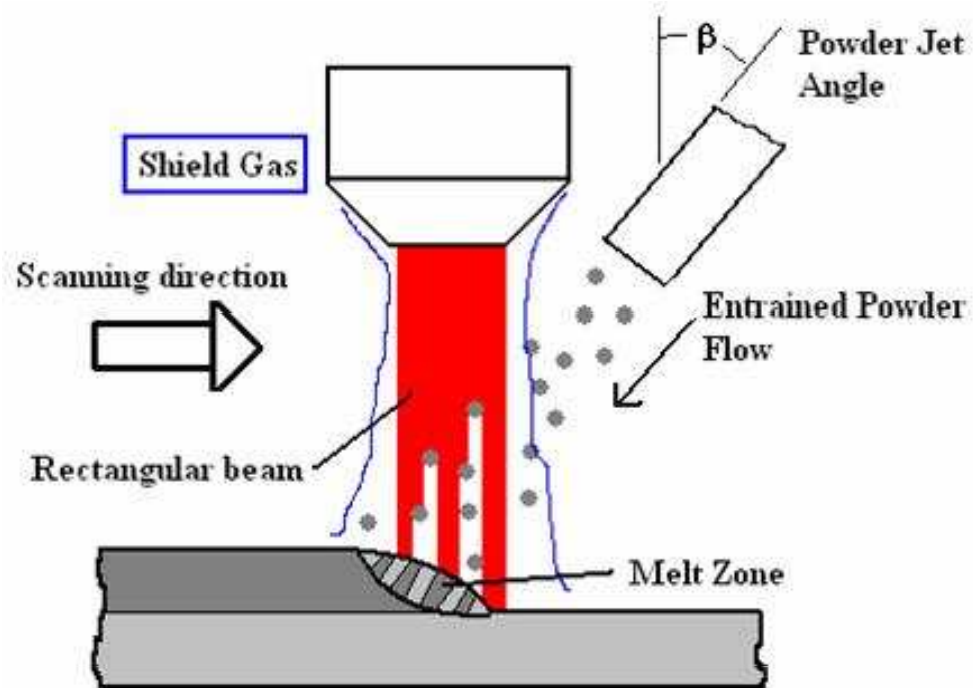
Kovy

Polovodiče

Polymery

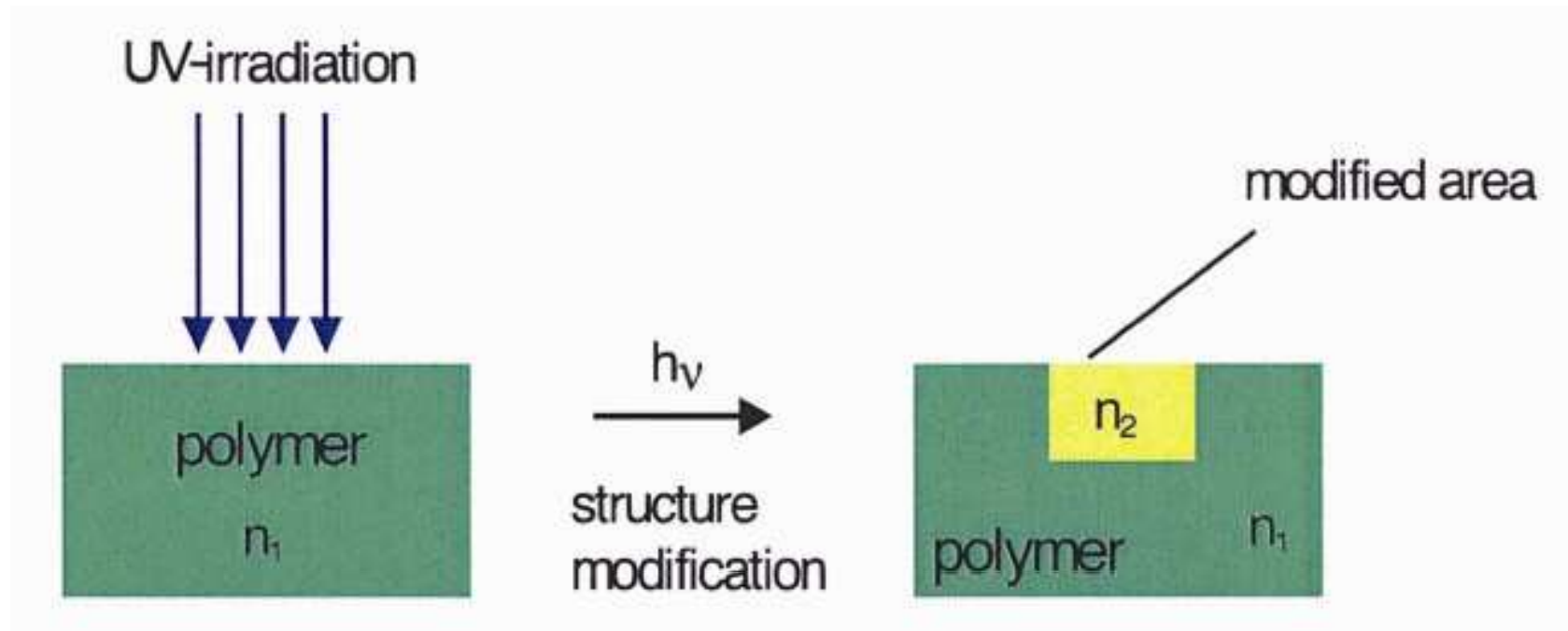


# Natařování povrchových vrstev



# Změny fyzikálních vlastností

Změna indexu lomu polymeru





# Změny fyzikálních vlastností

Vytrvzování polymerního materiálu působením UV laseru

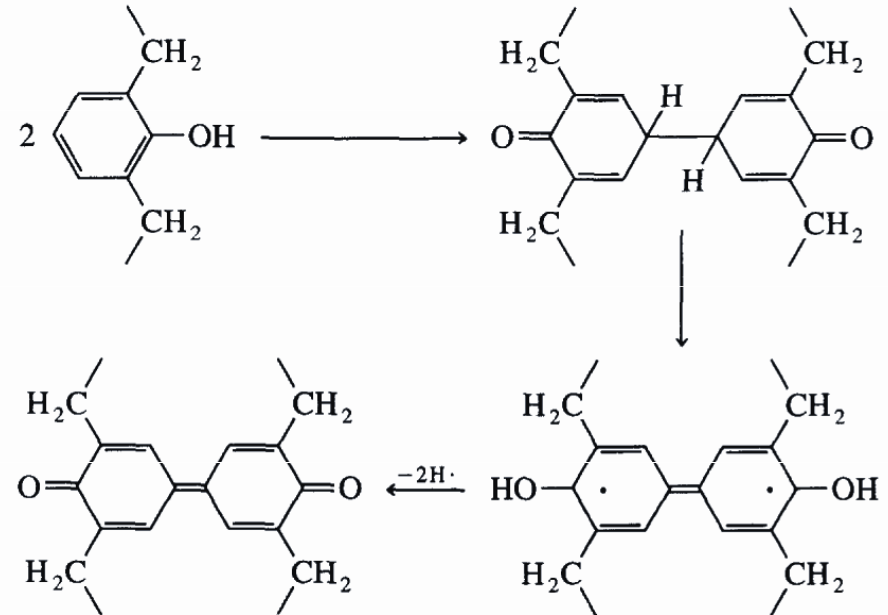
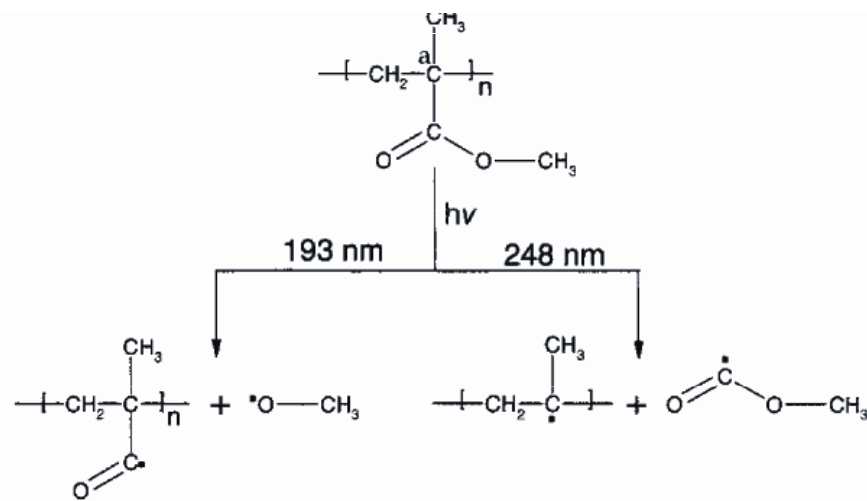
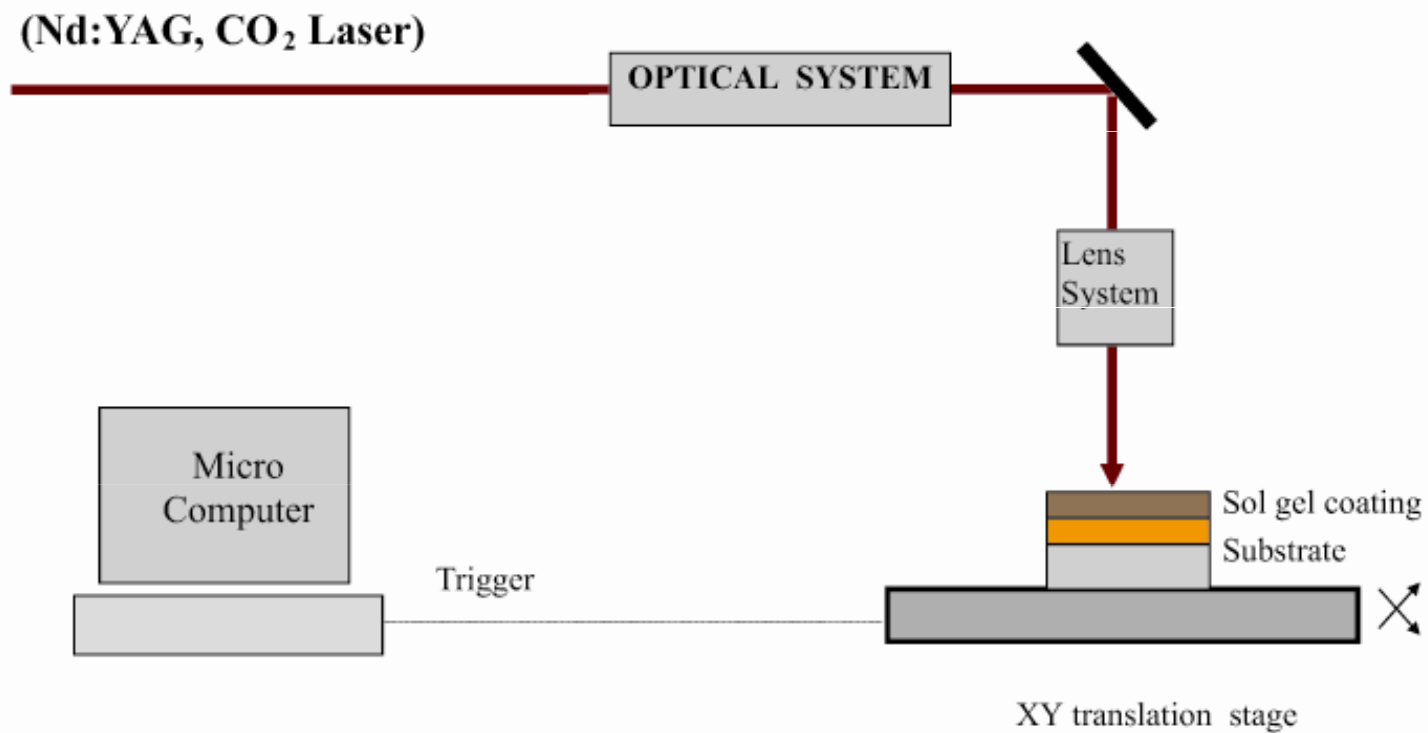


Fig. 11. Simplified photochemical modification scheme of irradiated PMMA.

# Změny fyzikálních vlastností

Přechod sol-gel



**Fig. 1.** Experimental setup of the process

# Obrábění laserovým paprskem

Řezání

Vrtání

Rytí a leptání

Sváření

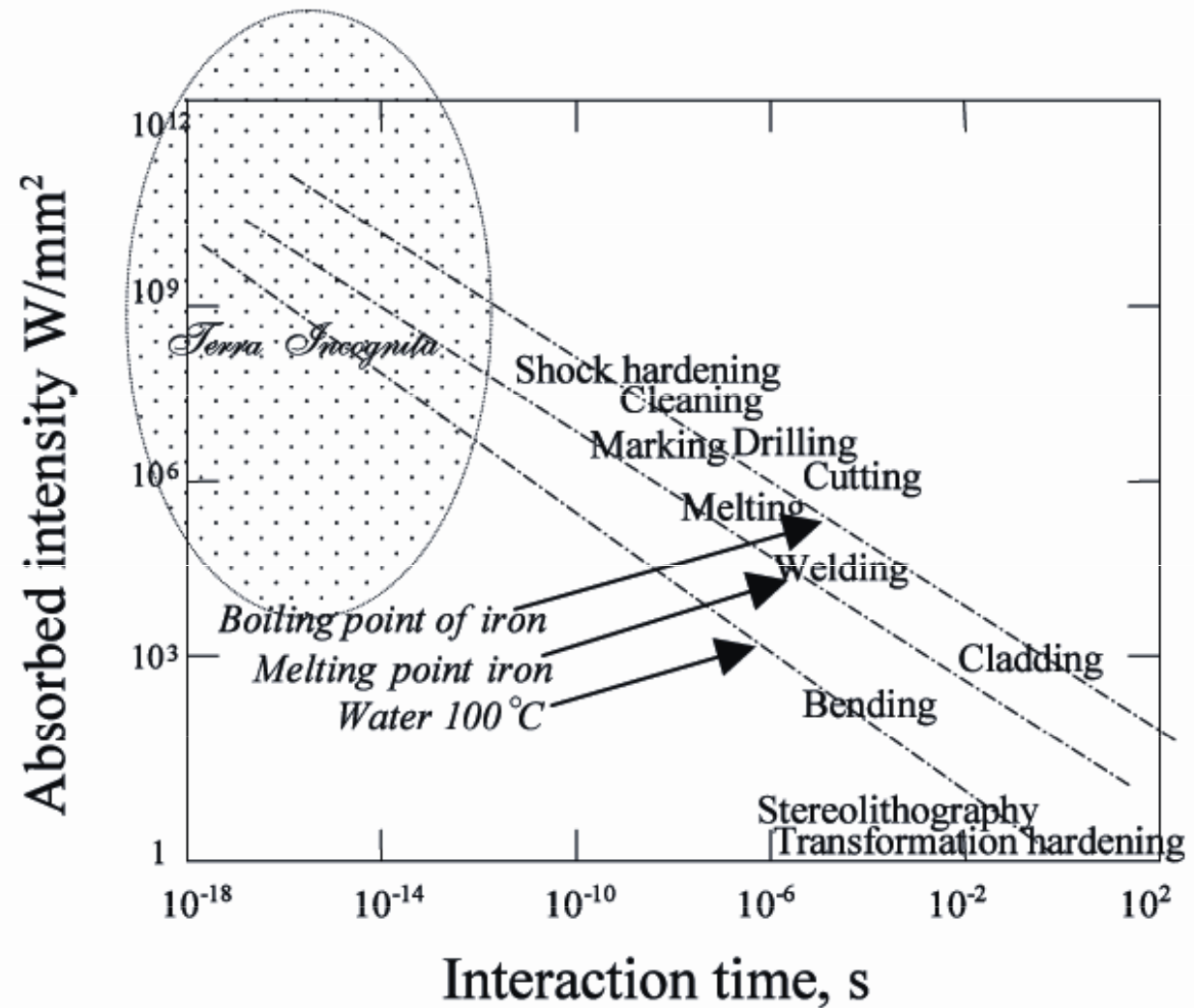
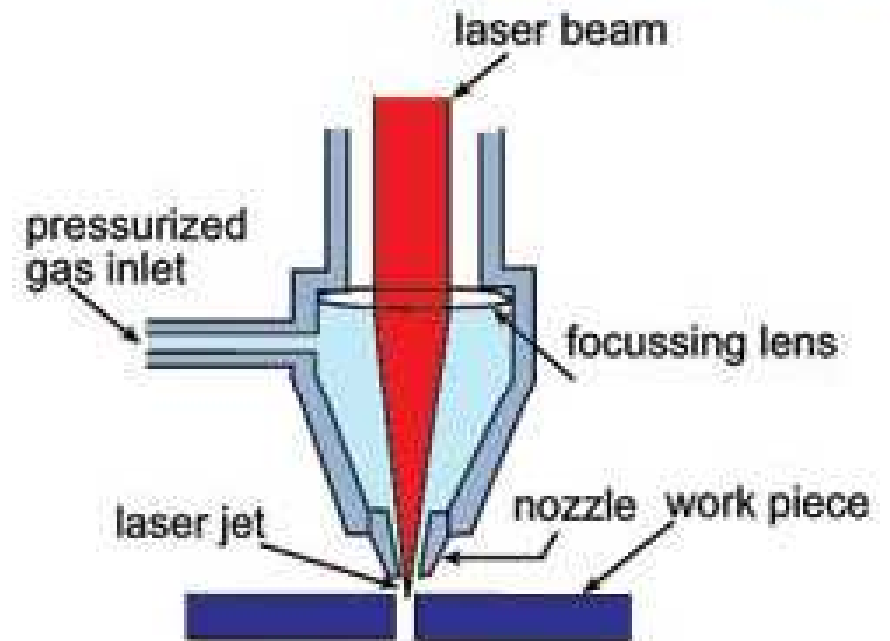
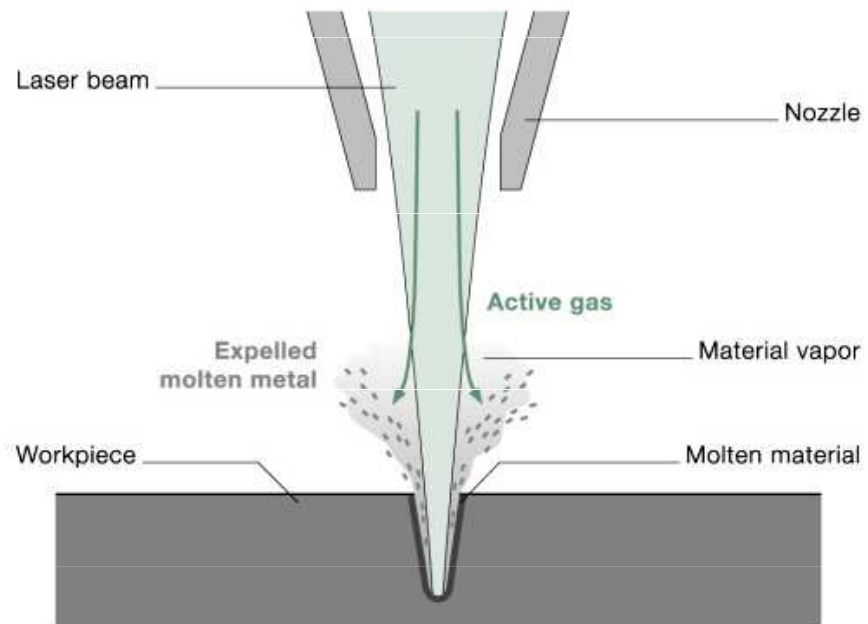


Figure 1. The range of processes.

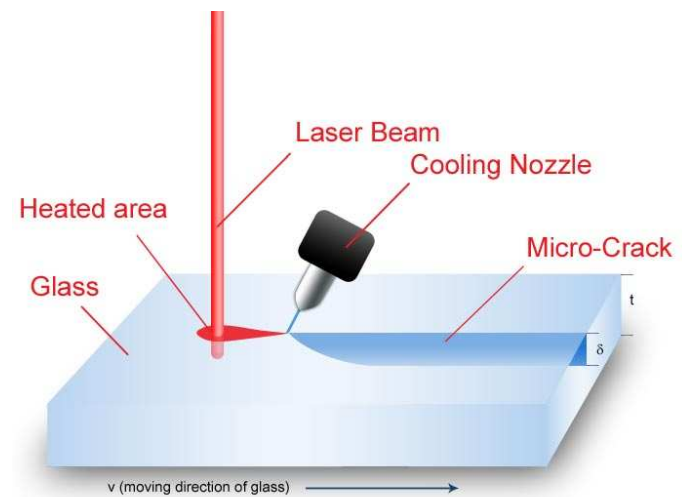
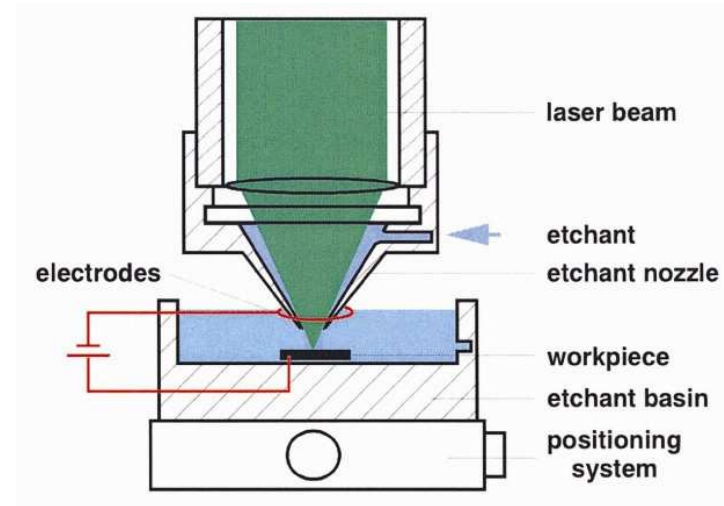
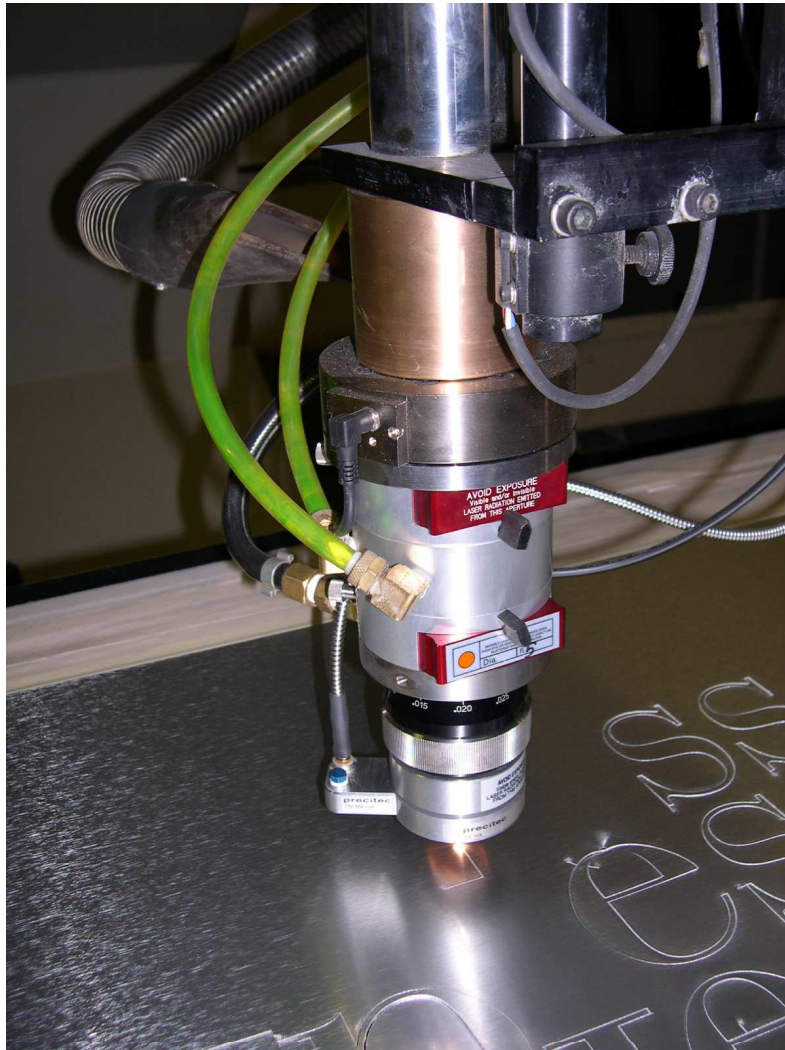
# Řezání laserovým paprskem



# Vrtání laserem



# Rytí a leptání



# Sváření laserovým paprskem (laser welding)

Svařování různorodých materiálů

Navařování malých součástek

